# **~ WAITRONY** 慧創就

## Micro Embedded Infrared Receiver Module

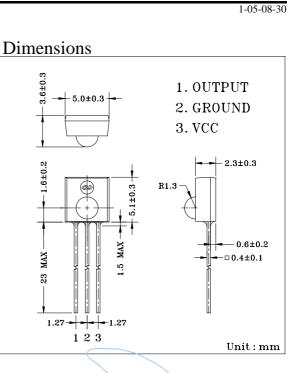
#### Module No.: PIC-8011ASE

- 1. Features:
- Microminiature size  $\triangleright$
- $\triangleright$ Embedded protection
- $\triangleright$ CMOS Design
- Built-in exclusive IC  $\geq$
- Wide half angle & long reception  $\triangleright$ distance
- $\geq$ Good noise-proof capability
- $\triangleright$ High immunity against ambient light
- $\triangleright$ High protection ability to EMI
- $\geq$ Side view
- $\triangleright$ Wide voltage operating: 2.7V ~ 5.5V

## 2. Applications

.. . ...

- AV instruments (Audio, TV, VCR, = CD player)
- Home appliances (Air-conditioner, ...... Fan, Light.)
- Remote control for wireless devices



(Ta)

25°C)

#### 3 Absolute Maximum Patings

5. Ausolute Maximum	Raings	()	(a=25 C)
Parameter	Symbol	Ratings	/ Unit
Supply Voltage	Vcc	6.0	V
Operating Temperature	Topr	-10 ~ +60	°C
Storage Temperature	Tstg	-20~+75	°C
Soldering Temperature *1	Tsol	240	°C

\*1 At the position of 2mm from the bottom of the package within 5 seconds.

#### 4. Electro-optical Characteristics

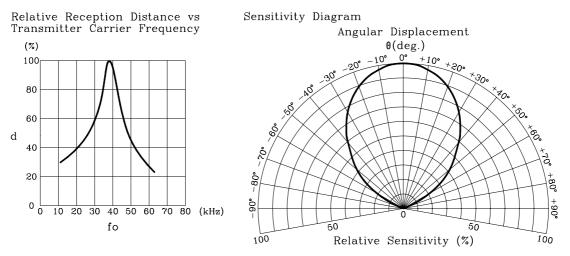
4. Electro-optical Characteristics					(Ta=25°C)	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply Voltage	Vcc		2.7		5.5	V
Current Consumption	Icc	Input Signal = 0		1.0	1.2	mA
Reception Distance	d	200±5Lux, Vcc=3.0V	10	16		m
Half Angle	$\Delta \theta h$			±45		deg
B.P.F. Center Frequency	Fo			37.9		kHz
Peak Wavelength	λp			940		nm
Signal Output	So		Active Low			
High Level Output Voltage	Voh		Vcc-0.5			V
Low Level Output Voltage	Vol			0.2	0.4	V
High Level Pulse Width	Twh	Puret Waya - 600ua	500	600	700	μs
Low Level Pulse Width	Twl	Burst Wave $= 600 \mu s$	500	600	700	μs

5. Reliability Test Items		(Ta=25°C)
Test Items	Test Conditions	Ratings
High Temperature Storage	Ta=60°C, Vcc=3.0V	t=240hr.
Low Temperature Storage	Ta=-10°C, Vcc=3.0V	t=240hr.
High Temperature High Humid Storage	Ta=40°C, 90%RH, Vcc=3.0V	t=240hr.
Temperature Cycling	-20°C (30min) ~ +70°C (30min)	20 cycles
Soldering Heat	240±5°C	5 sec.

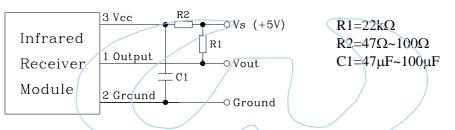


# Micro Embedded Infrared Receiver Module

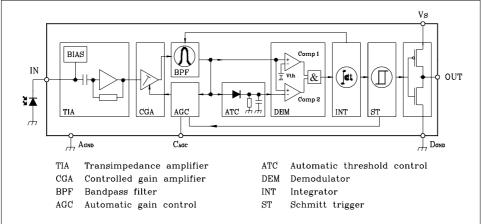
### Module No.: PIC-8011ASE



In case of noisy power supply, please serially insert 100 $\Omega$  resistor and about 47 $\mu$ F electrolytic capacitor in Vcc line and ground as follows:-



#### **Block Diagram**



Caution: This device is CMOS design. The signal output port of this device should drive the input port of the next stage device UNILATERALLY. Directly connecting the output port of this device with that of other device is not allowed and will cause the device to be damaged.

#### Standard Inspection

Among electrical characteristics, total quantity will be inspected as below:-

- Distance between emitter and detector
- ⊙ Current consumption
- ⊙ H level output voltage
- ⊙ L level output voltage

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### Module No.: PIC-8011ASE

#### **Testing Method**

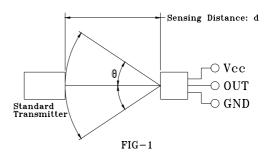
Distance between emitter and detector specifies maximum distance that output waveform satisfies the standard (FIG-3) under the conditions below against the standard transmitter.

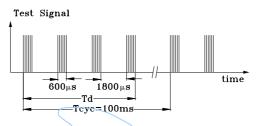
- a. Measuring place Indoor without extreme reflection of light.
- b. Ambient light source

Detecting surface illumination is 200±5Lux under ordinary white fluorescence lamp of no high frequency lightning.

c. Standard transmitter

Transmitter wave indicated in FIG-2 of standard transmitter is arranged to satisfy Vo≥50mVp-p under the measuring circuit specified in FIG-3





Tcyc-Td>30ms is recommended for optimal function

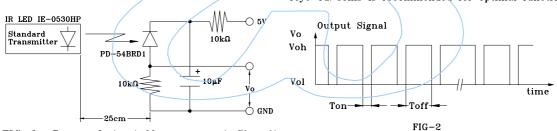
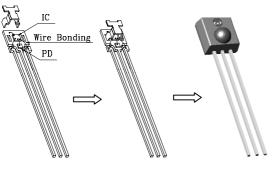


FIG-3 Power Output Measurement Circuit

#### Embedded Design

This design (Fig-4) is to install a metal case on the carrier lead frame to cover the semiconductor components, in order to shield it electromagnetically within the epoxy resin encapsulation.



Die Bonding Embedded Cover After Protection Encapsulation

FIG-4 Embedded Design

#### Precautions for Use

- a. Store and use where there is no force causing transformation or change in quality.
- b. Store and use where there is no corrosive gas or sea (salt) breeze.
- c. Store and use where there is no extreme humidity.
- d. Solder the lead pin within the condition of ratings. After soldering, do not add exterior force.
- e. Do not wash this device. Wipe the stains of diode side with a soft cloth. You can use the solvent, ethyl alcohol, or methyl alcohol only.
- f. To prevent static electricity damage to the pre-amp, make sure that the human body, the soldering iron are connected to ground before using.